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In data sheets and application notes which still contain NXP or Philips Semiconductors references, use the references to Nexperia, as shown below.

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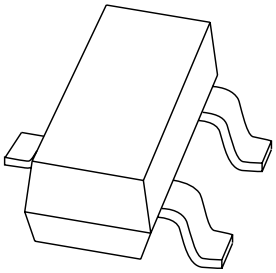
Kind regards,

Team Nexperia

DATA SHEET



BCX17; BCX18
PNP general purpose transistors

Product data sheet
Supersedes data of 1999 May 31

2004 Jan 16

PNP general purpose transistors BCX17; BCX18

FEATURES

- High current (max. 500 mA)
- Low voltage (max. 45 V).

APPLICATIONS

- Saturated switching and driver applications e.g. for industrial service
- Thick and thin-film circuits.

DESCRIPTION

PNP transistor in a SOT23 plastic package.
NPN complement: BCX19.

MARKING

TYPE NUMBER	MARKING CODE(1)
BCX17	T1*
BCX18	T2*

Note

1. * = p : Made in Hong Kong.
   * = t : Made in Malaysia.
   * = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector

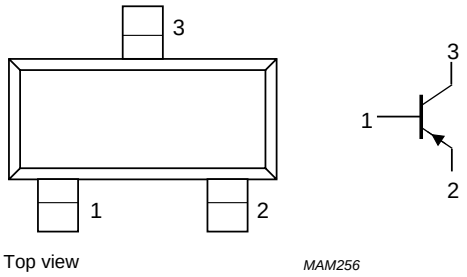


Fig.1 Simplified outline (SOT23) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BCX17	–	plastic surface mounted package; 3 leads	SOT23
BCX18			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BCX17		–	−50	V
	BCX18		–	−30	V
V_{CEO}	collector-emitter voltage	open base			
	BCX17		–	−45	V
	BCX18		–	−25	V
V_{EBO}	emitter-base voltage	open collector	–	−5	V
I_C	collector current (DC)		–	−500	mA
I_{CM}	peak collector current		–	−1	A
I_{BM}	peak base current		–	−200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 1	–	250	mW
T_{stg}	storage temperature		−65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		−65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

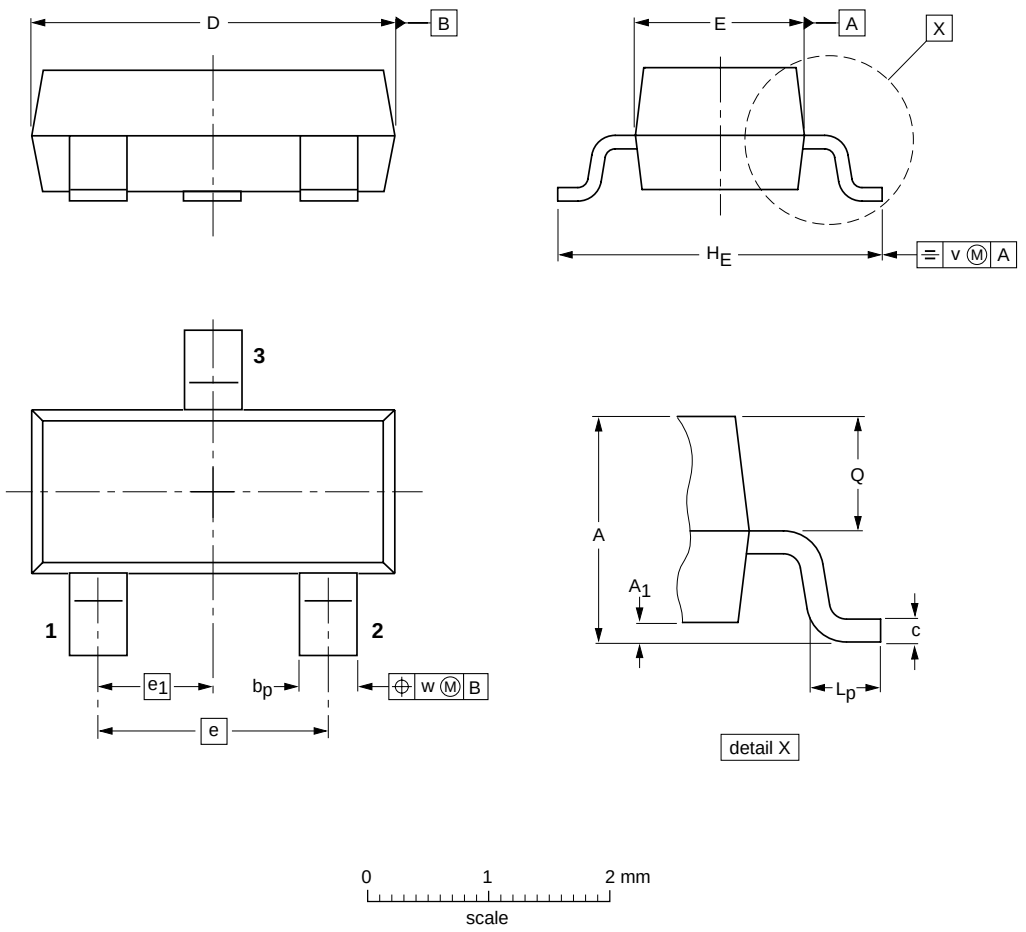
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	I_E = 0; V_{CB} = −20 V	–	–	−100	nA
		I_E = 0; V_{CB} = −20 V; T_j = 150 °C	–	–	−5	μA
I_{EBO}	emitter cut-off current	I_C = 0; V_{EB} = −5 V	–	–	−100	nA
h_{FE}	DC current gain	I_C = −100 mA; V_{CE} = −1 V	100	–	600	
		I_C = −300 mA; V_{CE} = −1 V	70	–	–	
		I_C = −500 mA; V_{CE} = −1 V	40	–	–	
V_{CEsat}	collector-emitter saturation voltage	I_C = −500 mA; I_B = −50 mA	–	–	−620	mV
V_{BE}	base-emitter voltage	I_C = −500 mA; V_{CE} = −1 V; note 1	–	–	−1.2	V
C_c	collector capacitance	I_E = I_e = 0; V_{CB} = −10 V; f = 1 MHz	–	9	–	pF
f_T	transition frequency	I_C = −10 mA; V_{CE} = −5 V; f = 100 MHz	80	–	–	MHz

Note

1. V_{BE} decreases by approximately −2 mV/°C with increasing temperature.

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads **SOT23**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max.	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				~~04-11-04~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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